

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10550153			
<b>Filing Date:</b>	20-Sep-2005			
<b>Title of Invention:</b>	Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product			
<b>First Named Inventor/Applicant Name:</b>	Toshikazu Okubo			
<b>Filer:</b>	Cameron Kerrigan/Mary Padilla			
<b>Attorney Docket Number:</b>	38915.00045			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1615	4	52	208
Independent claims in excess of 3	1614	4	220	880
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1088